

Material Composition Data



Product: GXO-3304

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GXO-3304 - 3225 CMOS Oscillator

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Ceramic 3225 SMD Lid	Carbon	C	7440-44-0	0.001	0.02
	Cobalt	Co	7440-48-4	0.946	17.17
	Iron	Fe	7439-89-6	2.933	53.22
	Manganese	Mg	7439-95-4	0.014	0.25
	Nickel	Ni	7440-02-0	1.610	29.21
	Silicon	Si	7440-21-3	0.007	0.13
Clk Osc IC	SiO2	SiO2	14808-60-7	0.200	21.39
	Silicon	Si	7440-21-3	0.735	78.61
Quartz (SiO2)	Quartz (SiO2)	SiO2	14808-60-7	0.398	100.00
SMD Base Ceramic	Aluminium oxide	Al	7429-90-5	18.324	92.50
	Calcium-oxide	CaO	1305-78-8	0.099	0.50
	Chromium(III)oxide	Cr2O3	1308-38-9	0.099	0.50
	Magnesium-oxide	MgO	1309-48-4	0.099	0.50
	Molybdenum	Mo	7439-98-7	0.198	1.00
	Silicon dioxide	SiO2	14808-60-7	0.991	5.00
SMD Base Electrode	Cobalt	Co	7440-48-4	1.290	100.00
SMD Base Gold Plating	Gold	Au	7440-57-5	0.046	80.70
	Thallium	Tl	7440-28-0	0.011	19.30
SMD Base Seal Ring	Carbon	C	7440-44-0	0.000	0.00
	Cobalt	Co	7440-48-4	0.265	17.14
	Iron	Fe	7439-89-6	0.823	53.23
	Manganese	Mg	7439-95-4	0.004	0.26
	Nickel	Ni	7440-02-0	0.452	29.24
	Silicon	Si	7440-21-3	0.002	0.13
SMD Base Silver Brazing	Copper	Cu	7440-50-8	0.043	14.93
	Silver	Ag	7440-22-4	0.245	85.07
Silver Epoxy	Epoxy resin	Epoxy resin trade secret	0	0.060	30.00
	Silver	Ag	7440-22-4	0.140	70.00
Silver Plating	Silver	Ag	7440-22-4	0.010	100.00
Total Mass:				30.045 mg	

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